



Material Content Data Sheet



Sales Product Name		BB 844 E6327		Issued		25. September 2017			
MA#		MA000387207							
Package		PG-SOT23-3-3		Weight*		8.70 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		19		
	noble metal	gold	7440-57-5	0.016	0.18		1844		
	inorganic material	silicon	7440-21-3	0.137	1.57	1.75	15747	17610	
leadframe	non noble metal	nickel	7440-02-0	1.142	13.13		131307		
	non noble metal	iron	7439-89-6	1.578	18.13	31.26	181328	312635	
wire	noble metal	gold	7440-57-5	0.016	0.18	0.18	1815	1815	
	encapsulation	organic material	carbon black	1333-86-4	0.089	1.02		10215	
		inorganic material	antimonytrioxide	1309-64-4	0.133	1.53		15323	
		plastics	brominated resin	-	0.167	1.92		19153	
		plastics	epoxy resin	-	1.389	15.96		159613	
		inorganic material	silicondioxide	60676-86-0	3.777	43.43	63.86	434146	638450
leadfinish	non noble metal	tin	7440-31-5	0.150	1.72	1.72	17200	17200	
plating	noble metal	silver	7440-22-4	0.107	1.23	1.23	12290	12290	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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